

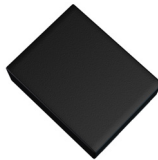
Features

- $BV_{CEO} > 45V$
- Low profile 0.4mm high package for thin applications
- Ultra-Small Surface Mount Package
- **Totally Lead-Free & Fully RoHS compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **Qualified to AEC-Q101 Standards for High Reliability**

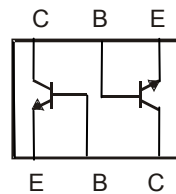
Mechanical Data

- Case: X2-DFN1310-6
- Nominal package height: 0.4mm
- Case Material: Molded Plastic, "Green" Molding Compound.
- UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish - NiPdAu, Solderable per MIL-STD-202, Method 208 (e4)
- Weight: 0.0015 grams (approximate)

X2-DFN1310-6



Top View



Device Schematic
Top View

Ordering Information (Note 4)

| Part Number | Marking | Reel Size (inches) | Tape Width (mm) | Quantity per Reel |
|-------------|---------|--------------------|-----------------|-------------------|
| BC847CDLP-7 | 1M | 7 | 8 | 3000 |

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 4. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>.

Marking Information



(Top View)

1M = Product Type Marking Code

Maximum Ratings (@T_A = +25°C unless otherwise specified.)

| Characteristic | Symbol | Value | Unit |
|---------------------------|------------------|-------|------|
| Collector-Base Voltage | V _{CB0} | 50 | V |
| Collector-Emitter Voltage | V _{CE0} | 45 | V |
| Emitter-Base Voltage | V _{EB0} | 6 | V |
| Collector Current | I _C | 100 | mA |

Thermal Characteristics – Total Device (@T_A = +25°C unless otherwise specified.)

| Characteristic | Symbol | Value | Unit |
|--|-----------------------------------|-------------|------|
| Power Dissipation (Note 5) Total Device | P _D | 350 | mW |
| Thermal Resistance, Junction to Ambient (Note 5) | R _{θJA} | 357 | °C/W |
| Operating and Storage Temperature Range | T _J , T _{STG} | -65 to +150 | °C |

Note: 5. For a device surface mounted on minimum recommended pad layout FR-4 PCB with single sided 1oz copper, in still air conditions; the device is measured when operating in a steady-state condition.

Thermal Characteristics – Total Device

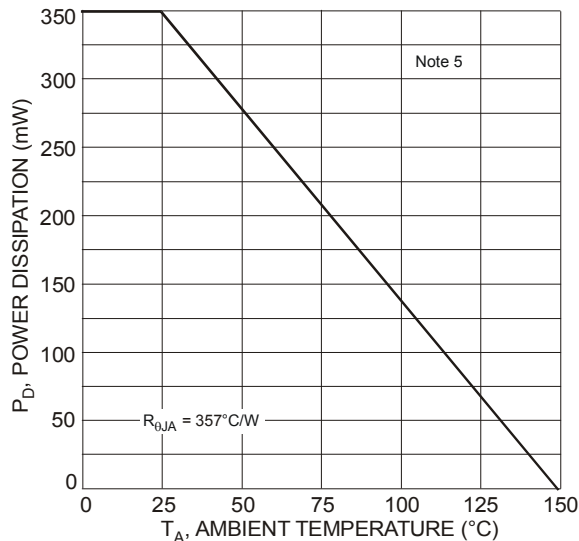


Figure 1 Power Dissipation vs. Ambient Temperature

Electrical Characteristics (@ $T_A = +25^\circ\text{C}$ unless otherwise specified.)

| Characteristic (Note 6) | Symbol | Min | Typ | Max | Unit | Test Condition |
|--------------------------------------|---------------|----------|------------|------------|---------------------|---|
| Collector-Base Breakdown Voltage | BV_{CBO} | 50 | — | — | V | $I_C = 100\mu\text{A}, I_B = 0$ |
| Collector-Emitter Breakdown Voltage | BV_{CEO} | 45 | — | — | V | $I_C = 10\text{mA}, I_B = 0$ |
| Emitter-Base Breakdown Voltage | BV_{EBO} | 6 | — | — | V | $I_E = 100\mu\text{A}, I_C = 0$ |
| DC Current Gain | h_{FE} | 420 | 650 | 800 | — | $V_{CE} = 5.0\text{V}, I_C = 2.0\text{mA}$ |
| Collector-Emitter Saturation Voltage | $V_{CE(sat)}$ | — | 55 130 | 250 600 | mV | $I_C = 10\text{mA}, I_B = 0.5\text{mA}$ $I_C = 100\text{mA}, I_B = 5.0\text{mA}$ |
| Base-Emitter Saturation Voltage | $V_{BE(sat)}$ | — | 700 900 | — | mV | $I_C = 10\text{mA}, I_B = 0.5\text{mA}$ $I_C = 100\text{mA}, I_B = 5.0\text{mA}$ |
| Base-Emitter Voltage | $V_{BE(on)}$ | 580 — | 660 — | 700 770 | mV | $V_{CE} = 5.0\text{V}, I_C = 2.0\text{mA}$ $V_{CE} = 5.0\text{V}, I_C = 10\text{mA}$ |
| Collector-Cutoff Current | I_{CES} | — | — | 15 | nA | $V_{CE} = 50\text{V}$ |
| Collector-Cutoff Current | I_{CBO} | — | — | 15 5 | nA μA | $V_{CB} = 30\text{V}$ $V_{CB} = 30\text{V}, T_A = +150^\circ\text{C}$ |
| Gain Bandwidth Product | f_T | 100 | — | — | MHz | $V_{CE} = 5.0\text{V}, I_C = 10\text{mA},$ $f = 100\text{MHz}$ |
| Collector-Base Capacitance | C_{CBO} | — | 2.0 | — | pF | $V_{CB} = 10\text{V}, f = 1.0\text{MHz}$ |

Note: 6. Measured under pulsed conditions. Pulse width $\leq 300\mu\text{s}$. Duty cycle $\leq 2\%$.

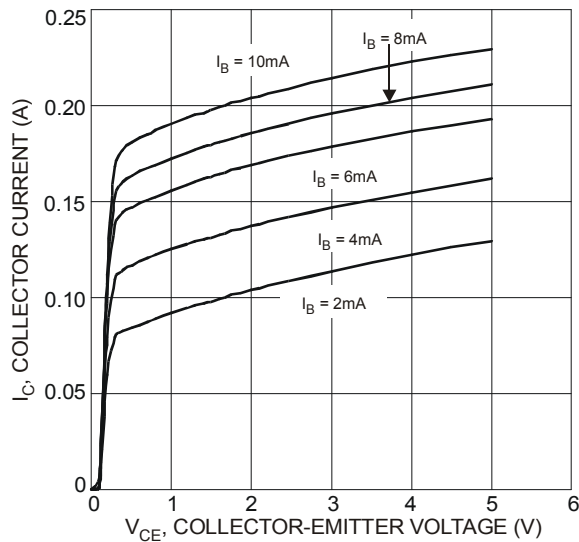


Figure 2 Typical Collector Current vs. Collector-Emitter Voltage

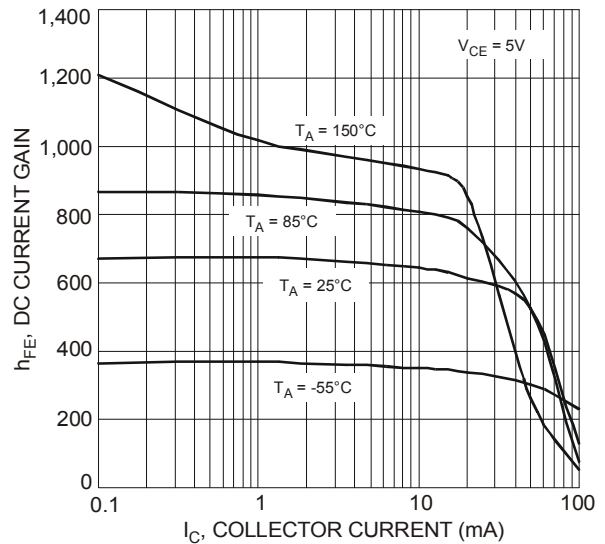


Figure 3 Typical DC Current Gain vs. Collector Current

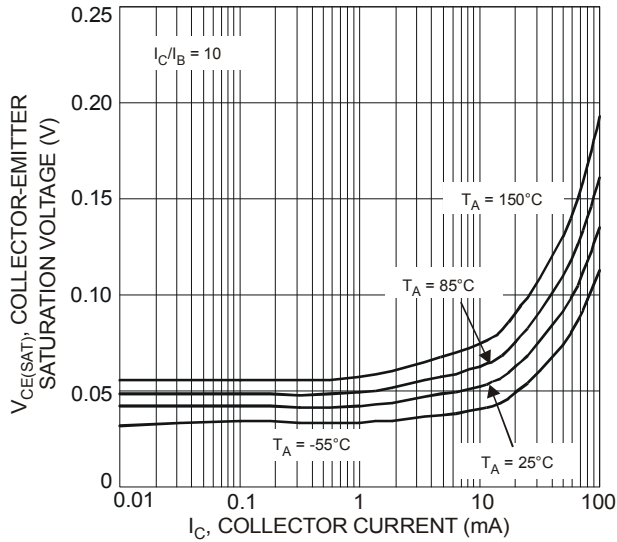


Figure 4 Typical Collector-Emitter Saturation Voltage vs. Collector Current

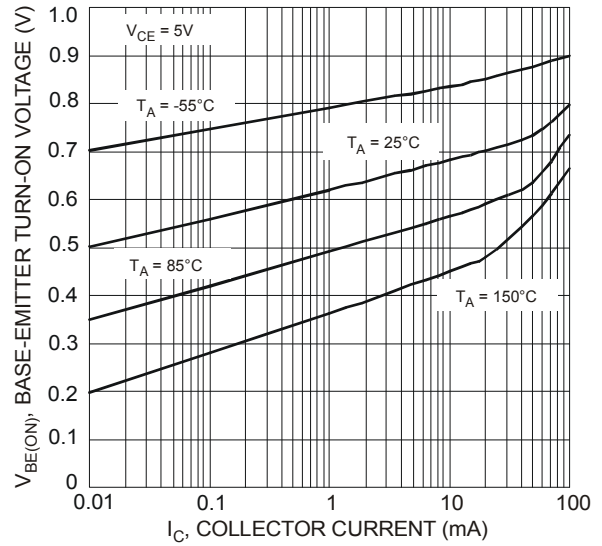


Figure 5 Typical Base-Emitter Turn-On Voltage vs. Collector Current

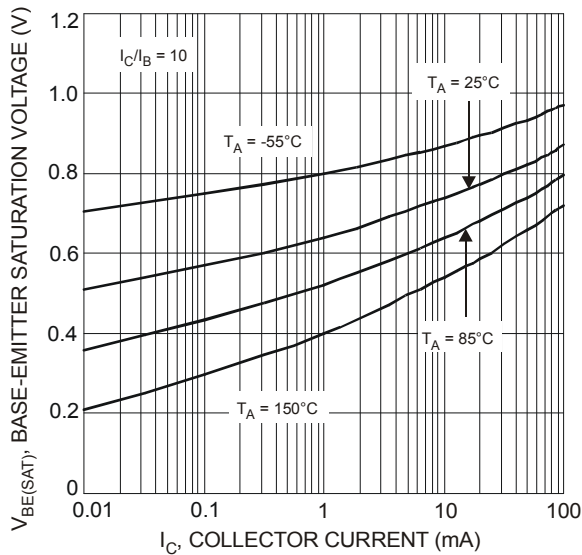


Figure 6 Typical Base-Emitter Saturation Voltage vs. Collector Current

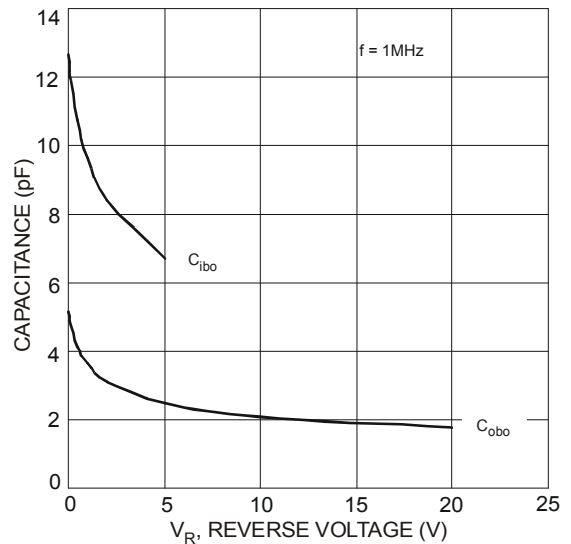


Figure 7 Typical Capacitance Characteristics

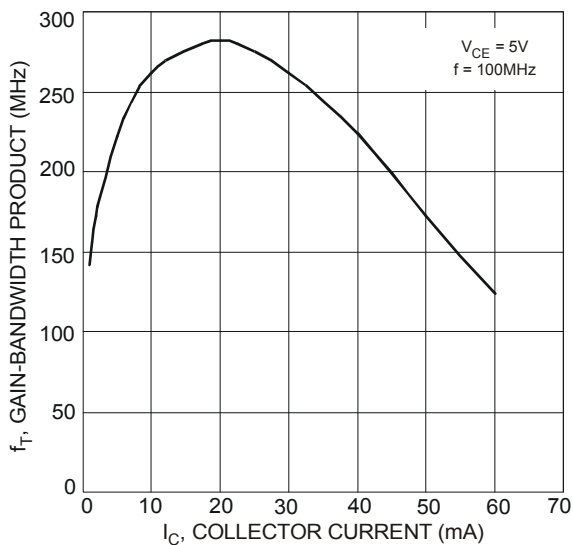
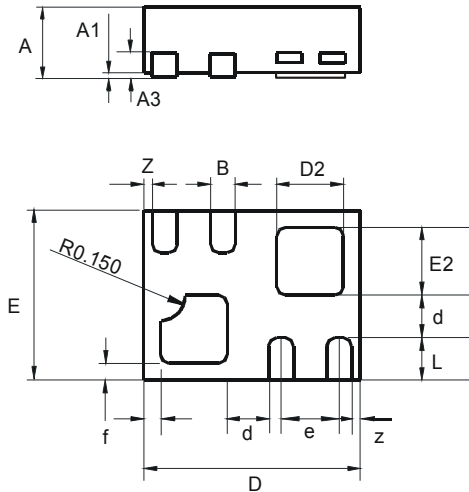


Figure 8 Typical Gain-Bandwidth Product vs. Collector Current

Package Outline Dimensions

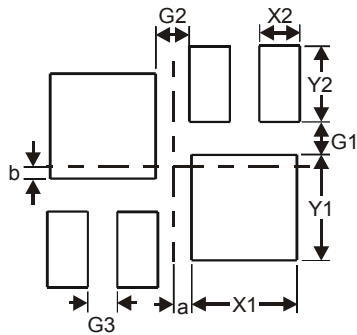
Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for latest version.



| X2-DFN1310-6 | | | |
|----------------------|------|-------|------|
| Dim | Min | Max | Typ |
| A | — | 0.40 | — |
| A1 | 0 | 0.05 | 0.02 |
| A3 | — | — | 0.13 |
| b | 0.10 | 0.20 | 0.15 |
| D | 1.25 | 1.38 | 1.30 |
| d | — | — | 0.25 |
| D2 | 0.30 | 0.50 | 0.40 |
| E | 0.95 | 1.075 | 1.00 |
| e | — | — | 0.35 |
| E2 | 0.30 | 0.50 | 0.40 |
| f | — | — | 0.10 |
| L | 0.20 | 0.30 | 0.25 |
| Z | — | — | 0.05 |
| All Dimensions in mm | | | |

Suggested Pad Layout

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.



| Dimensions | Value (in mm) |
|------------|---------------|
| G1 | 0.16 |
| G2 | 0.17 |
| G3 | 0.15 |
| X1 | 0.52 |
| X2 | 0.20 |
| Y1 | 0.52 |
| Y2 | 0.375 |
| a | 0.09 |
| b | 0.06 |

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